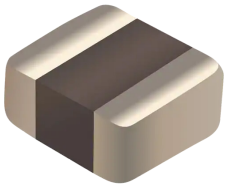
HRI0806SPI High-Reliability Shielded Power Inductor



Features

- Tin-Lead solder termination finish.
- Shielded construction for low radiation.
- Metal alloy powder core for high saturation current.

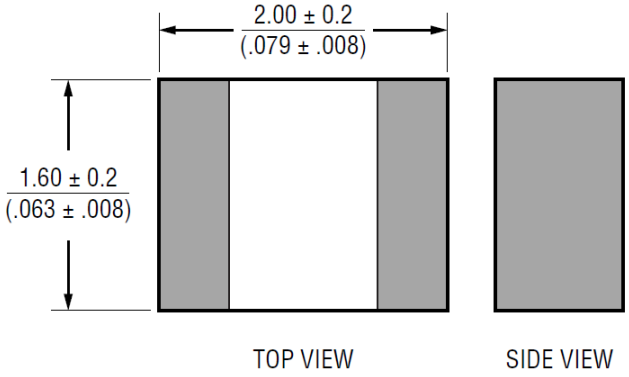
Applications

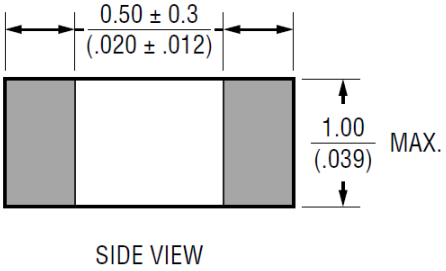
- Aerospace
- Avionics
- Military

Electrical Characteristics @ +25 °C

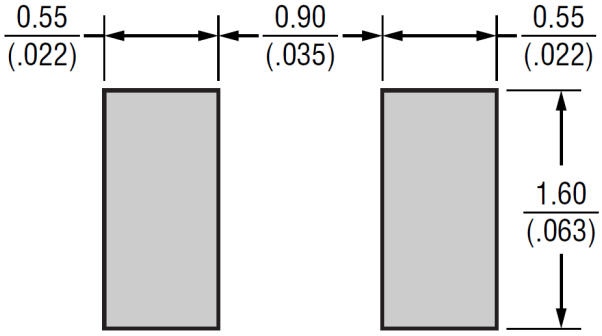
AEM Part No.	Inductance @500kHz/0.25V		DCR (mΩ) Typ.	DCR (mΩ) Max.	Irms (A) Typ.	Isat (A) Typ.
	L(uH)	Tol. %				
HRI0806SPI-R47Mxx	0.47	20	29	40	3.60	4.50
HRI0806SPI-R56Mxx	0.56	20	42	57	3.00	4.00
HRI0806SPI-1R0Mxx	1.0	20	57	70	2.60	3.40
HRI0806SPI-1R5Mxx	1.5	20	83	110	2.10	2.80
HRI0806SPI-2R2Mxx	2.2	20	137	168	1.60	2.20
HRI0806SPI-3R3Mxx	3.3	20	202	225	1.40	1.90
HRI0806SPI-4R7Mxx	4.7	20	315	360	1.10	1.50

Product Dimensions





Recommended Pad Layout



DIMENSIONS: MM (INCHES)

Certified to AS9100D ISO 9001:2015

MIL-STD-790

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Standard Screening Options

- Option 1: 100% visual inspection per MIL-PRF-83446, MIL-STD-981.
- Option 2: Group A and B Screening per MIL-PRF-83446, MIL-STD-981.
- Option 3: Group A, B, and C Screening per MIL-PRF-83446, MIL-STD-981.
- Option 4: Group A, B, and Qualification Screening per MIL-PRF-83446, MIL-STD-981.

Note: See AEM detail specification for more details.

Part Number Identifier

HRI 0806SPI 2R2M x x

- HRI: High Reliability Shielded Power Inductor
- 0806SPI : Package/Model
- Inductance Code: R is a decimal point (.) and the digit or number after it is the value of the inductance
- Screening Options: 1, 2, 3,4 (see screening options on the left)
- *Terminal Code: 1: Sn/Pb plated; 2: Sn plated*

General Specifications and Materials

1- Operating temperature:..... -40°C to +125°C (Temperature rise included).
2- Storage temperature:..... (Component) -40°C to +125°C.
3- Temperature rise:..... 40°C at rated Irms*.
4- Inductance drops:..... 30% at Isat.
5- Moisture sensitivity level:..... MSL=1
6- ESD Classification (HBM): .....N/A
7- Core: .....Metal alloy powder.
8- Wire: .....Enameled copper.
9- Terminal finish: .....Tin/Lead (Sn/Pb).

*** Note: Part temperature should be verified in the end application. Circuit design, component, PCB traces size and thickness, airflow and other cooling provisions affect the part temperature.**